## TECHNICAL PRODUCT INFORMATION



# Microstrip® 3200

#### **Product Description**

Fujifilm Electronic Materials' Microstrip® 3200 is a bulk photoresist stripper designed for excellent compatibility with various metals and sensitive materials for advanced integration technologies. Microstrip® 3200 has improved EH&S properties over conventional NMP or hydroxyl amine based chemistries and it is the preferred alternative for NMP as solvent stripper for mildly treated photoresist as in wet etch or electroplating applications.

Microstrip® 3200 can be used with silicon, silicon dioxide, silicon nitride, titanium, tungsten, gold and other metal substrates. With its high metal compatibility it is particularly applicable on copper, silver and aluminum alloys.

Microstrip® 3200 provides good bath stability with low evaporation rates, and it is compatible with ultrasonic cleaning systems. Its low viscosity minimizes drag-out losses and typically requires only a DI-water rinse. Trace metals specifications for Microstrip® 3200 are below 20 ppb.

## **Recommended Process**

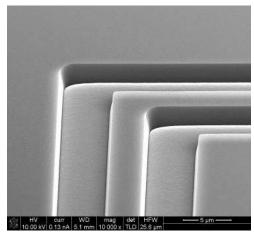
For most process applications, Microstrip® 3200 can be used to strip positive photoresist under standard conditions. Typical process conditions are 5 to 30 min at temperatures between 50°C and 85°C, followed by a DI water rinse.

The application of ultrasonic during the strip process can be useful to accelerate the stripping process or to improve the performance on photoresists with a higher degree of cross linking

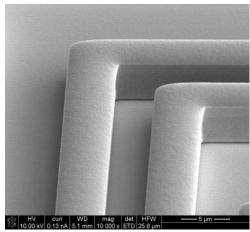
## Recommended process flow

- 1. Heat two baths of Microstrip<sup>®</sup> 3200 to 70°C ± 5°C.
- 2. Insert wafers in a carrier and immerse in each bath for 5 to 15 minutes using mild agitation.
- 3. Rinse in deionized water to 18 M $\Omega$ cm resistivity.
- 4. Spin dry.

# Microstrip<sup>®</sup> 3200 for resist strip after Cu plating



**Before Clean** 



Post Clean 5 minutes at 65°C

#### **Product Data:**

## Microstrip® 3200 Metal Etch Rates (75°C)

Metal	Etch Rate (Å/minute)
Al	< 1
Ti	< 1
TiN	< 1
TiW	< 1
Ni	< 1
Cu	1
Au	< 1
Ag	< 1

Thickness measurements were made using a CDE ResMap 168 four-point probe

## Microstrip® 3200 Dielectric Compatibility (75°C)

Dielectric	Etch Rate (Å/minute)
FSG	< 1
BD1	< 1
Coral	< 1
TEOS	< 1

Thickness measurements were made using a Filmetrics F-series FB3B measurement system

## Microstrip® 3200 Physical Properties

Specific Gravity @ 25°C	1.10
Flash Point (°C) (closed cup)	85
Viscosity @ 25°C (cSt)	1.7
Freezing Point (°C)	< 0
pH ( 5% solution @ 25°C)	4-5

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